

SPECIFICATION FOR APPROVAL

CUSTOMER : _____

PRODUCT TYPE : SMD SEAM SEALING CXO 5.0*3.2

NOMINAL FREQ. : 50.000000MHz

TXC P/N : 7C50000001

REVISION : A1

CUSTOMER P/N : _____

PM / SALES : _____

DATE : _____

CUSTOMER SIGNATURE & Date

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

Attachment: Product Specification Sheet

- 1
- 2
- 3
- 4
- 5

RoHS Compliant




PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : SMD SEAM SEALING CXO 5.0*3.2

NOMINAL FREQ. : 50.000000MHz

TXC P/N : 7C50000001

REVISION : A1

| PE/RD | QA | MFG |
|---|---|--|
|  |  |  |
| 15-Oct-07 | 19-Oct-07 | 15-Oct-07 |

NOTE:

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required.

RoHS Compliant

■ ELECTRICAL SPECIFICATIONS

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : $25\pm 5^{\circ}\text{C}$

Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : $25\pm 3^{\circ}\text{C}$

Relative humidity : 40%~70%

Measure equipment

Electrical characteristics measured by MD 37WX-05M or equivalent.

Crystal cutting type

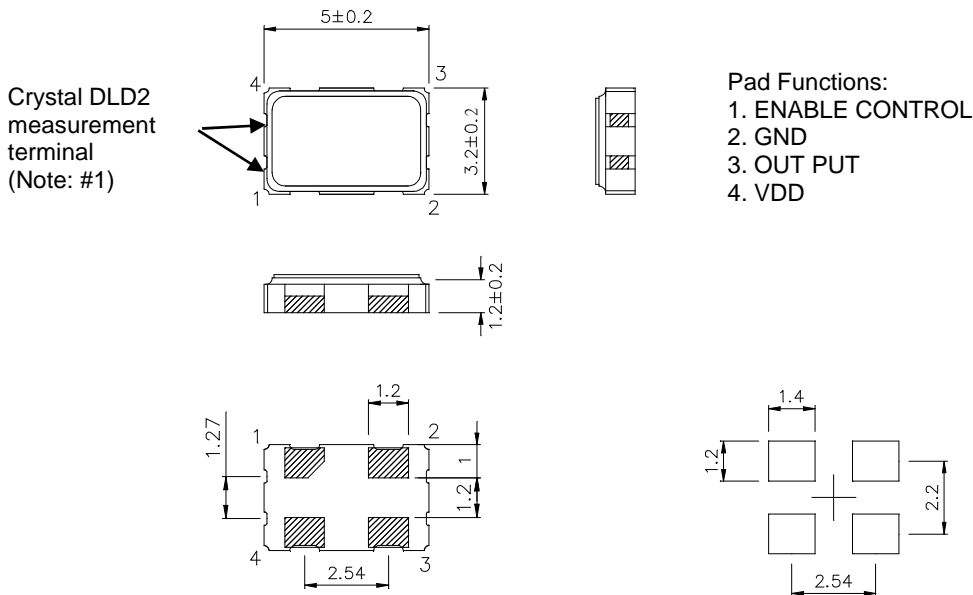
The crystal is using AT CUT (thickness shear mode).

Unit Weight:

0.058±0.001 g/pcs

| | Parameters | SYM. | Electrical Spec. | | | | Notes |
|----|---------------------------|-------|------------------|------|--------|---------|-------------------|
| | | | MIN | TYPE | MAX | UNITS | |
| 1 | Nominal Frequency | - | 50.000000 | | | MHz | - |
| 2 | Frequency Stability | - | ±25 | | | ppm | - |
| 3 | Operating Temperature | Topr | -10 | 25 | 70 | °C | - |
| 4 | Storage Temperature | Tstg | -55 | ~ | 125 | °C | - |
| 5 | Supply Voltage | VDD | 3.3 ±10% | | | V | - |
| 6 | Input Current | Icc | - | - | 30 | mA | - |
| 7 | Enable Control | - | Yes | | | - | Pad 1 |
| 8 | Output Load : CMOS | CL | 15 | | | pF | - |
| 9 | Output Voltage High | VoH | 90%Vdd | - | - | V | - |
| 10 | Output Voltage Low | VoL | - | - | 10%Vdd | V | - |
| 11 | Rise Time | Tr | - | - | 10 | ns | 10%→90%VDD Level |
| 12 | Fall Time | Tf | - | - | 10 | ns | 90%→10%VDD Level |
| 13 | Symmetry (Duty ratio) | TH/T | 45 | ~ | 55 | % | - |
| 14 | Start-up Time | Tosc | - | - | 10 | ms | - |
| 15 | Enable Voltage High | Vhi | 70%Vdd | - | - | V | - |
| 16 | Disable Voltage Low | Vlo | - | - | 30%Vdd | V | - |
| 17 | Aging | - | ±3 | | | ppm/yr. | 1st. Year at 25°C |
| 18 | Output Disable Delay Time | T off | - | - | 150 | us | - |
| 19 | Output Enable Delay Time | T on | - | - | 150 | us | - |

■ DIMENSIONS

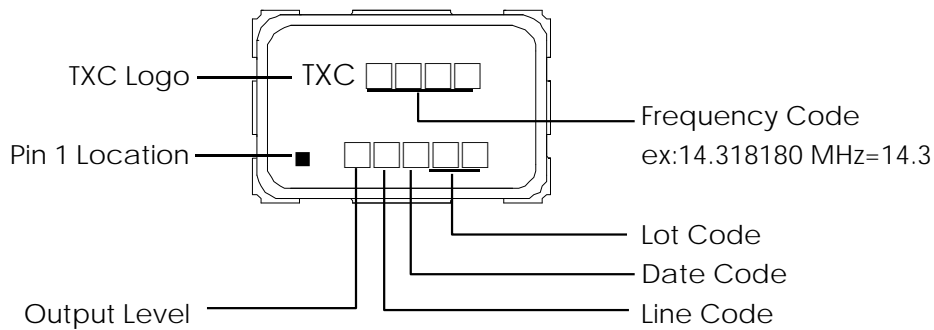


Note: #1. DLD2 / Drive Level Dependency 2

Maximum resistance minus minimum resistance.

Unit:mm

■ MARKING



Output Level:

| | | | | | | | | | |
|------|------|------|------|------|------|------|------|-------|------|
| VDD | 5.0V | 3.3V | 2.8V | 2.5V | 1.8V | 2.9V | 3.0V | 2.85V | 2.6V |
| CODE | A | B | C | D | E | F | G | H | J |

Date Code:

| YEAR | | | | MONTH | | | | | | | | | | | |
|------|------|------|------|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| | | | | JAN | FEB | MAR | APR | MAY | JUN | JUL | AUG | SEP | OCT | NOV | DEC |
| 2005 | 2009 | 2013 | 2017 | A | B | C | D | E | F | G | H | J | K | L | M |
| 2006 | 2010 | 2014 | 2018 | N | P | Q | R | S | T | U | V | W | X | Y | Z |
| 2007 | 2011 | 2015 | 2019 | a | b | c | d | e | f | g | h | j | k | l | m |
| 2008 | 2012 | 2016 | 2020 | n | p | q | r | s | t | u | v | w | x | y | z |

*This date code will be cycled every four years

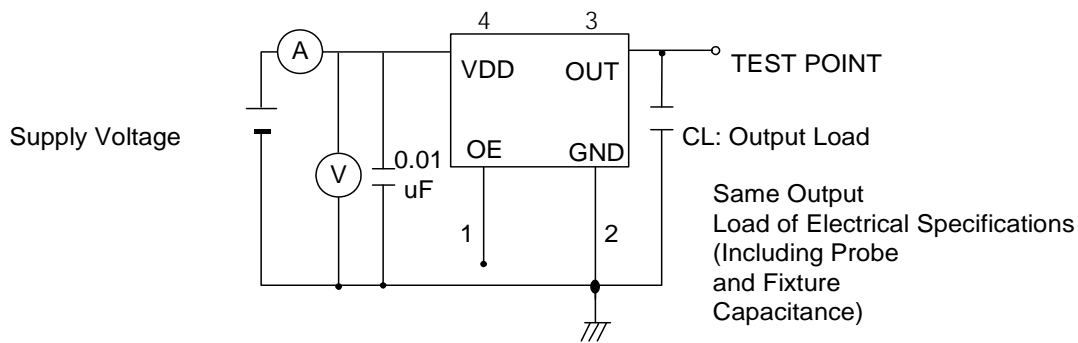
Production location: Taiwan

TEST DIAGRAM

Control input (output enable/disable)

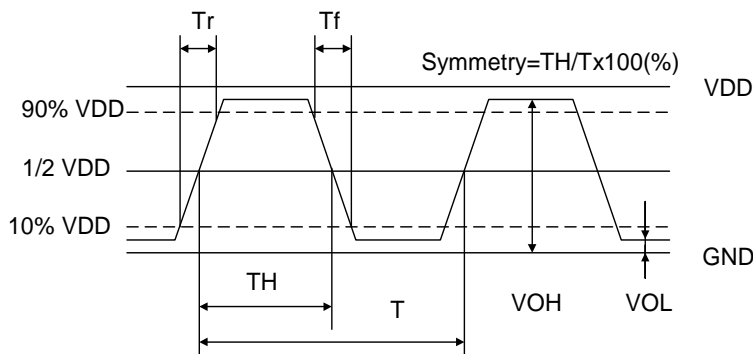
Logic 1 or open on pad 1: Oscillator output

Logic 0 on pad 1 : Disable output to high impedance



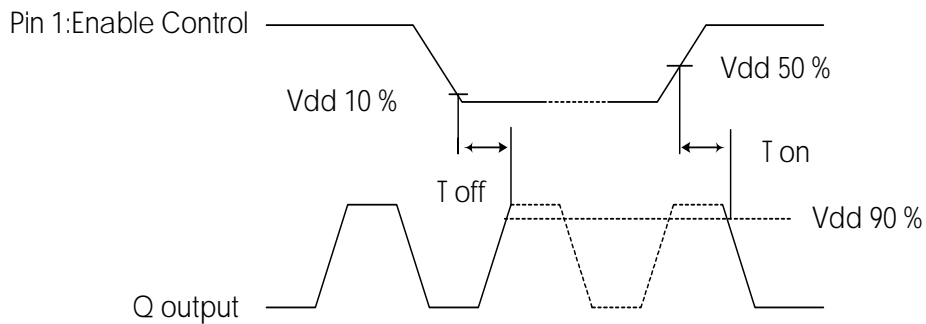
WAVEFORM CONDITIONS

Waveform measurement system should have a min. bandwidth of 5 times the frequency being tested.



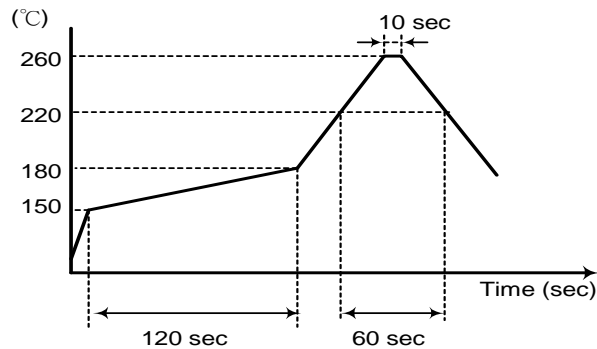
OUTPUT ENABLE / DISABLE DELAY

The following figure shows the oscillator timing during normal operation . Note that when the device is in standby, the oscillator stops. When standby is released, the oscillator starts and stable oscillator output occurs after a short delay.

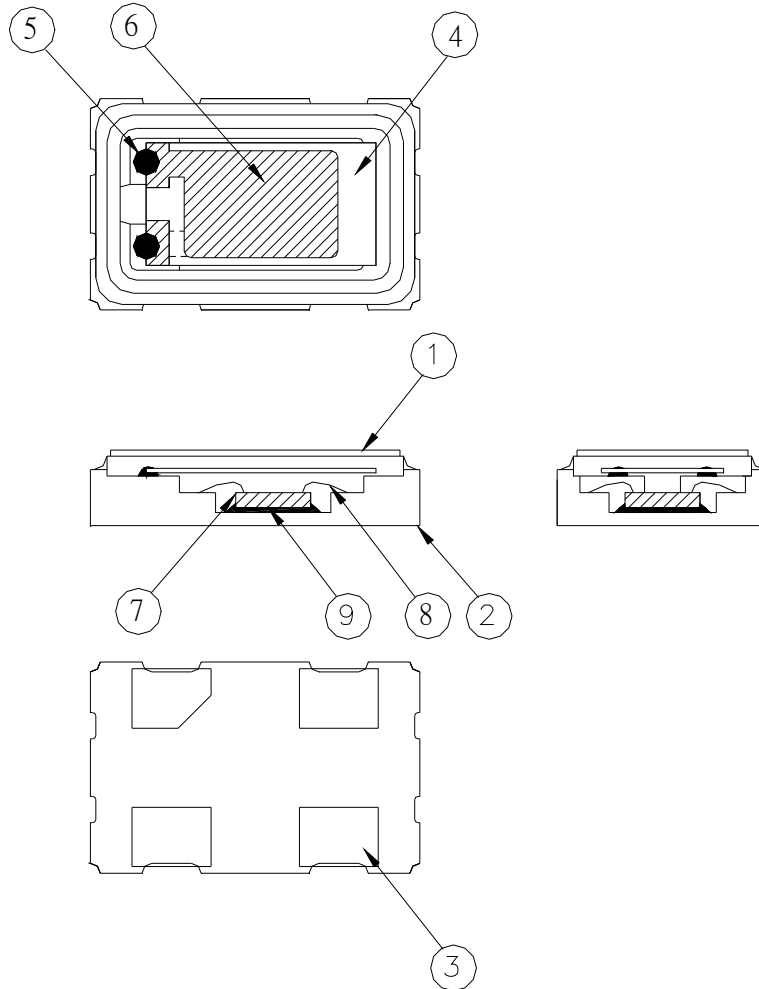


SUGGESTED REFLOW PROFILE

Total time : 200 sec. Max.
Solder melting point :220 °C

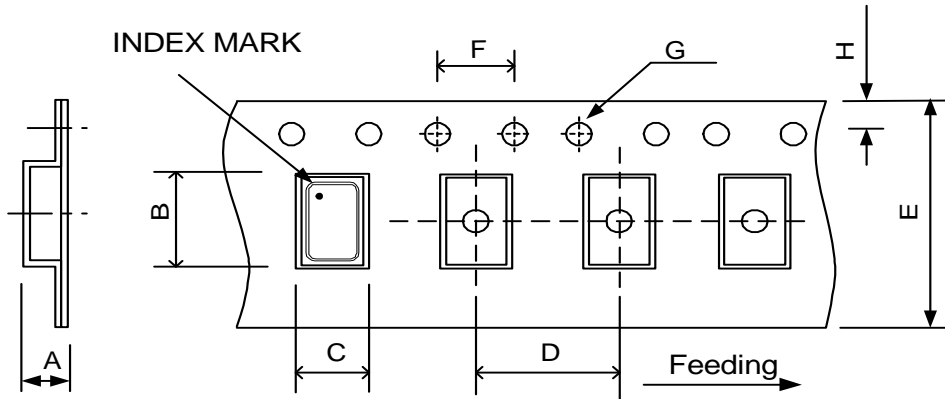


■ STRUCTURE ILLUSTRATION



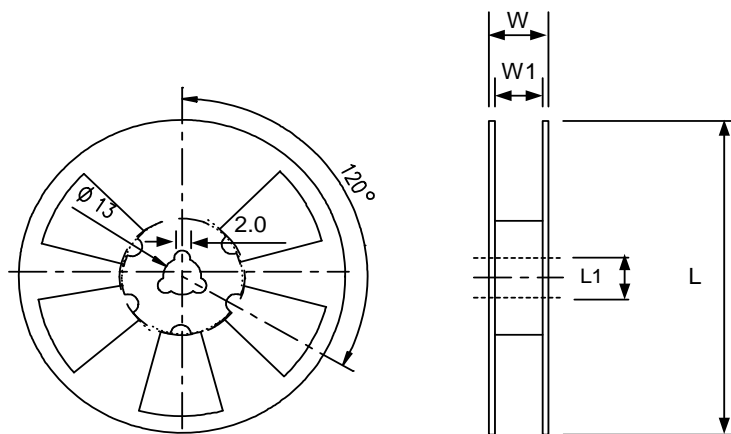
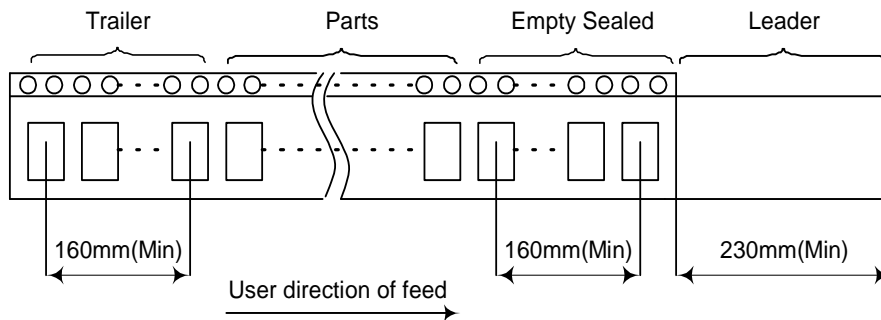
| NO | COMPONENTS | MATERIALS | QTY | FINISH/SPECIFICATIONS |
|----|---------------------|---|--------|---|
| 1 | Lid | Kovar (Fe/Co/Ni) | 1 | - |
| 2 | Base (Package) | Ceramic (Al ₂ O ₃) + Kovar (Fe/Co/Ni)+ Ag/Cu | 1 | - |
| 3 | PAD | Au | 4 | Tungsten metalize + Ni plating + Au plating |
| 4 | Crystal blank | SiO ₂ | 1 | - |
| 5 | Conductive adhesive | Ag | 4 | Silicon resin |
| 6 | Electrode | Noble Metal | 2 | - |
| 7 | IC chip | - | 1 | - |
| 8 | Bonding wire | Au | 5 or 6 | Pad 1 options : NC is 5 wires , EN is 6 wires. |
| 9 | Die attached | Conductive (Ag) | 1 | Epoxy resin |

■ PACKING : (EIA-481-2)



| | | | | | | | | | |
|------------|------|------|------|------|-------|------|------|------|-------------|
| DIMENSIONS | A | B | C | D | E | F | G | H | (UNIT : mm) |
| | 1.40 | 5.40 | 3.60 | 8.00 | 12.00 | 4.00 | 1.55 | 1.75 | |

REMARK :



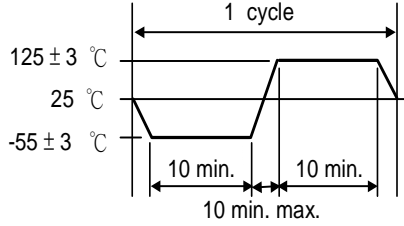
| | | | | | |
|------------|-----|----|------|----|--|
| DIMENSIONS | L | L1 | W | W1 | pcs / Reel (UNIT : mm) |
| | 180 | 13 | 16.5 | 12 | Standard Reel Quantity is 1,000 pcs per reel |

■ RELIABILITY SPECIFICATIONS

1.Mechanical Endurance

| No. | Test Item | Test Methods | REF. DOC |
|-----|------------------|--|--------------|
| 1 | Drop Test | 75 cm height, fall freely onto concrete floor 3 times. | JIS C6701 |
| 1 | Mechanical Shock | Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times. 0.5m sec. duration time | MIL-STD-202F |
| 1 | Vibration | Frequency range 10 ~ 2000 Hz Amplitude 1.52 mm/20G Sweep time 20 minute perpendicular axes each test time 4 hours (Total test time 12 hours) | MIL-STD-883E |
| 1 | Gross Leak | Standard Sample For Automatic Gross Leak Detector, Test Pressure: 2Kg / cm ² | MIL-STD-883E |
| 2 | Fine Leak | Helium Bombing 4.5 Kg / cm ² for 2 hr | |
| 2 | Solderability | Temperature 245 °C ± 5°C Immersing depth 0.5 mm minimum Immersion time 5 ± 1 seconds Flux Rosin resin methyl alcohol solvent (1 : 4) | MIL-STD-883E |

2.Environmental Endurance

| No. | Test Item | Test Methods | REF. DOC |
|-----|------------------------------|---|--------------|
| 2 | Resistance To Soldering Heat | Pre-heat temperature 125 °C Pre-heat time 60 ~ 120 sec. Test temperature 260 ± 5 °C Test time 10 ± 1 sec. | MIL-STD-202F |
| 2 | High Temp. Storage | + 125 °C ± 3 °C for 1000 ± 12 hours | MIL-STD-883E |
| 2 | Low Temp. Storage | - 40 °C ± 3 °C for 1000 ± 12 hours | |
| 2 | Thermal Shock | Total 100 cycles of the following temperature cycle  | MIL-STD-883E |
| 3 | High Temp & Humidity | 85°C ± 3°C, RH 85% , 1000Hrs | JIS C5023 |
| 3 | Pressure Cooker Storage | 121 ± 3°C , RH100% , 2 bar , 240Hrs | JIS C6701 |